

(0.80 mm) .0315"

MEC8-DV SERIES

VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC8-DV

Insulator Material:
Black LCP
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(4.22 mm) .166" to
(5.66 mm) .223"
Current Rating:
1.8 A per pin
(4 adjacent pins powered)
Voltage Rating:
185 VAC

PROCESSING

RoHS Compliant:

Yes

Lead–Free Solderable: Yes SMT Lead Coplanarity: (0.10 mm) .004" max (10-50) (0.15 mm) .006" max (60-70)" *(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



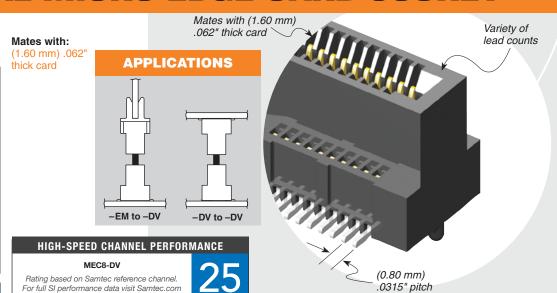
ALSO AVAILABLE (MOQ Required)

- 1 mm mating card thickness option
- Locking clip (Manual placement required)

Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some sizes, styles and options are non-standard, non-returnable.



02

10, 20, 30, 40, 50, 60, 70

or contact SIG@samtec.com

MEC8

— L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

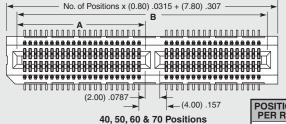
PLATING

OPTION



OTHER

OPTION



POSITIONS

PER ROW

POSITIONS PER ROW В (18.90) .744 (36.60)40 1.441 (22.90)(44.60) 50 .902 1.756 (52.60) (26.90) 60 1 059 2.071 (30.90) 1,217 (60.60) 2.386 70

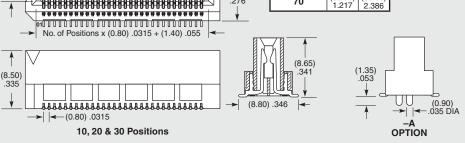
OTHER SOLUTIONS

• Right-angle

DV

Edge Mount

See samtec.com?MEC8-RA or samtec.com?MEC8-EM



Due to technical progress, all designs, specifications and components are subject to change without notice